

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/03/2022

Details for "LP3981IMM-2.8/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LP3981IMM-2.8/NOPB	SN	Level-1-260C-UNLIM	Texas Instruments Electronics	DGK 8	3 x 3 x 1	30.9

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.028343	100	1000000	0.091781	918
Sub-Total			0.028343	100	1000000	0.091781	918
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.135314	74.999861	749999	0.438175	4382
Thermoplastics	Epoxy	85954-11-6	0.045105	25.000139	250001	0.146059	1461
Sub-Total			0.180419	100	1000000	0.584234	5842
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	14.618636	96.550003	965500	47.3382	473382
Copper and Its Alloys	Iron	7439-89-6	0.360356	2.380001	23800	1.166908	11669
Copper and Its Alloys	Phosphorus	7723-14-0	0.004542	0.029998	300	0.014708	147
Precious Metals	Silver	7440-22-4	0.139297	0.919999	9200	0.451073	4511
Zinc and Its Alloys	Zinc	7440-66-6	0.018169	0.119999	1200	0.058835	588
Sub-Total			15.141	100	1000000	49.029724	490297
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.15	100	1000000	3.72394	37239
Sub-Total			1.15	100	1000000	3.72394	37239
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	12.338162	89.000002	890000	39.953549	399535
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	0.415893	2.999999	30000	1.346748	13467
Thermoplastics	Epoxy	85954-11-6	1.109048	7.999998	80000	3.591329	35913
Sub-Total			13.863103	100	1000000	44.891626	448916
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.518402	100	1000000	1.678694	16787
Sub-Total			0.518402	100	1000000	1.678694	16787
Total			30.881267			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See [Glossary of Terms for more details](#).

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, see [Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact [TI customer support](#).

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.